



**DMN3018SSD** 

#### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C		
2014	22mΩ @ V <sub>GS</sub> = 10V	6.7A		
30V	30mΩ @ V <sub>GS</sub> = 4.5V	5.2A		

# **Description and Applications**

This MOSFET has been designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- **Power Management Functions**
- **DC-DC Converters**

#### 30V DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

#### Features

- Low On-Resistance
- 100% UIS (Avalanche) Rated
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

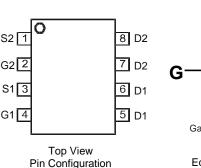
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.074 grams (Approximate)

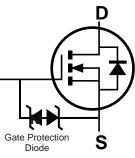




SO-8

Top View





Equivalent Circuit per Element

#### Ordering Information (Note 4)

Part Number	Case	Packaging
DMN3018SSD-13	SO-8	2500/Tape & Reel

S2

G2

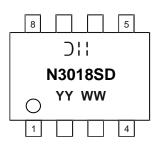
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. Notes:

2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## Marking Information



∃ = Manufacturer's Marking N3018SD = Product Type Marking Code YYWW = Date Code Marking YY or  $\overline{YY}$  = Year (ex: 16 = 2016) WW = Week (01 to 53)



## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	30	V
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
Continuous Drain Current (Note 5) // 10//	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	6.7 5.3	A
Continuous Drain Current (Note 5) $V_{GS} = 10V$	t < 10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	8.7 6.9	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	60	A
Maximum Body Diode Continuous Current			ls	2.0	A
Avalanche Current (Note 6) L = 0.1mH			I <sub>AR</sub>	19	A
Repetitive Avalanche Energy (Note 6) L = 0.1mH			E <sub>AR</sub>	18	mJ

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		PD	1.5	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	P	83	°C/W
memar Resistance, Junction to Ambient (Note 5)	t < 10s	$R_{\theta JA}$	50	°C/W
Thermal Resistance, Junction to Case (Note 5)		R <sub>θJC</sub>	14.5	°C/W
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

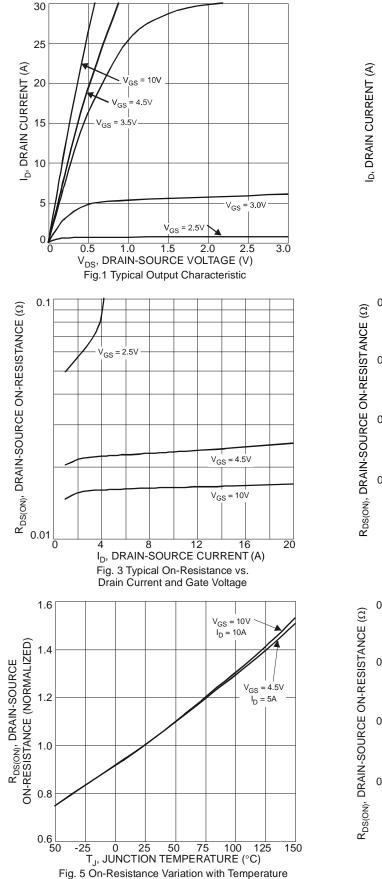
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						•
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	_	—	V	$V_{GS} = 0V, I_D = 250 \mu A$
Zero Gate Voltage Drain Current	IDSS	_	_	1	μA	$V_{DS} = 24V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±10	μA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	1.7	2.1	V	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$
Static Drain-Source On-Resistance	Deserve		16	22	mΩ	$V_{GS} = 10V, I_D = 10A$
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>		23	30		$V_{GS} = 4.5V, I_D = 6A$
Forward Transfer Admittance	Y <sub>fs</sub>		8.3	—	S	$V_{DS} = 5V, I_{D} = 6.9A$
Diode Forward Voltage	V <sub>SD</sub>	0.5	_	1.2	V	$V_{GS} = 0V, I_S = 1A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss		697	-	pF	$V_{DS} = 15V, V_{GS} = 0V,$ f = 1.0MHz
Output Capacitance	Coss	_	97	—		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	67	—		
Gate Resistance	Rq	_	1.47	—	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	6.0	—		V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V, I <sub>D</sub> = 9A
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	13.2	—	nC	
Gate-Source Charge	Q <sub>gs</sub>	_	2.2	—	nc	
Gate-Drain Charge	Q <sub>gd</sub>	_	1.8	—		
Turn-On Delay Time	t <sub>D(ON)</sub>	_	4.3	_		$\label{eq:VDD} \begin{split} V_{DD} &= 15V, \ V_{GS} = 10V, \\ R_L &= 15\Omega, \ I_D = 1A, \ R_G = 6\Omega \end{split}$
Turn-On Rise Time	t <sub>R</sub>	_	4.4	_	ns	
Turn-Off Delay Time	t <sub>D(OFF)</sub>		20.1	_		
Turn-Off Fall Time	t <sub>F</sub>	_	4.1	—	1	
Reverse Recovery Time	t <sub>RR</sub>		7.3	_	ns	
Reverse Recovery Charge	Q <sub>RR</sub>		7.9	—	nC	I <sub>F</sub> = 9A, di/dt = 500A/μs

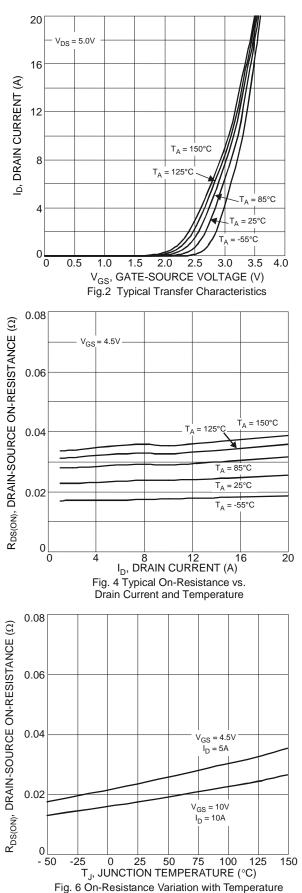
Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

6. Jac and E<sub>AR</sub> ratings are based on low frequency and duty cycles to keep  $T_J = +25^{\circ}$ C. 7. Short duration pulse test used to minimize self-heating effect.

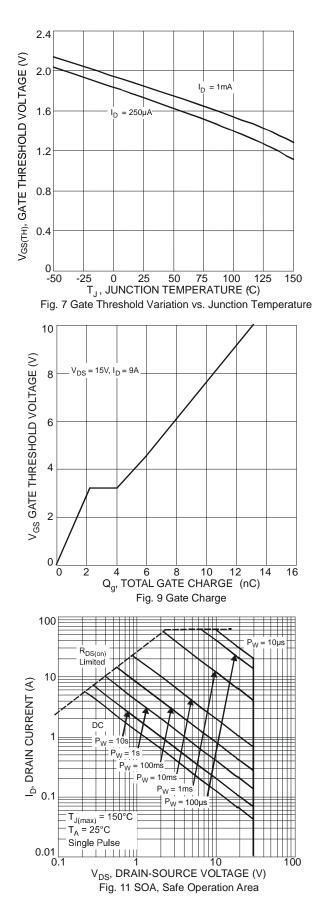
8. Guaranteed by design. Not subject to product testing.

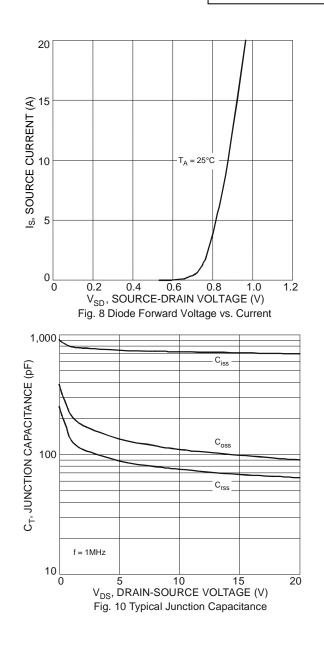




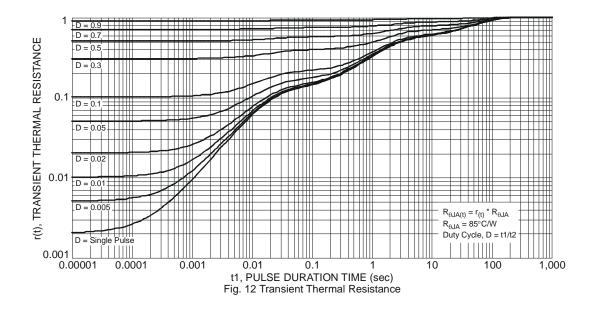






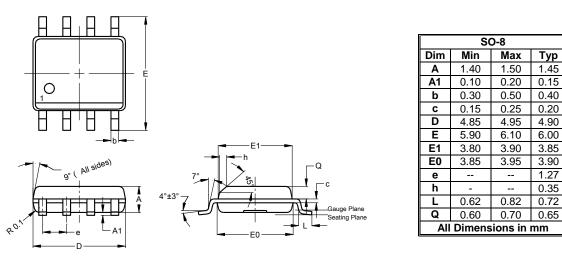






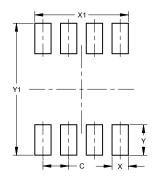
## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.



## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Y	1.505
Y1	6.50

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